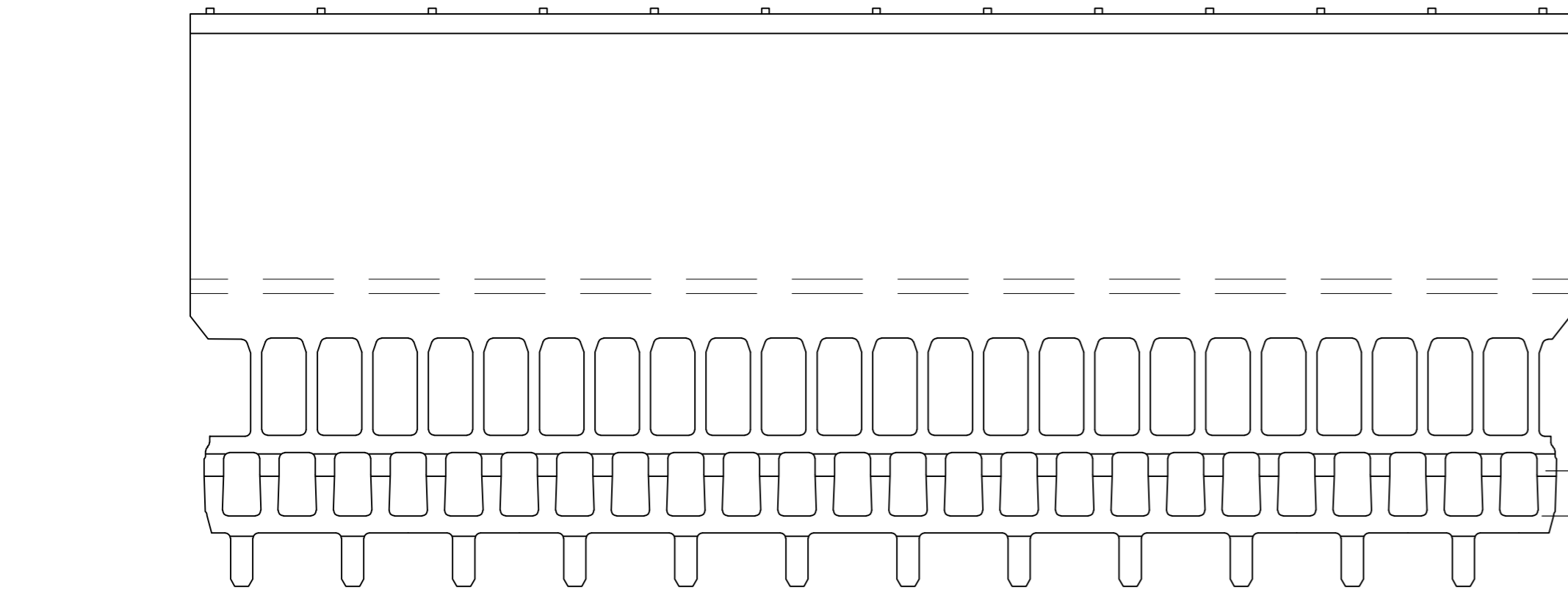
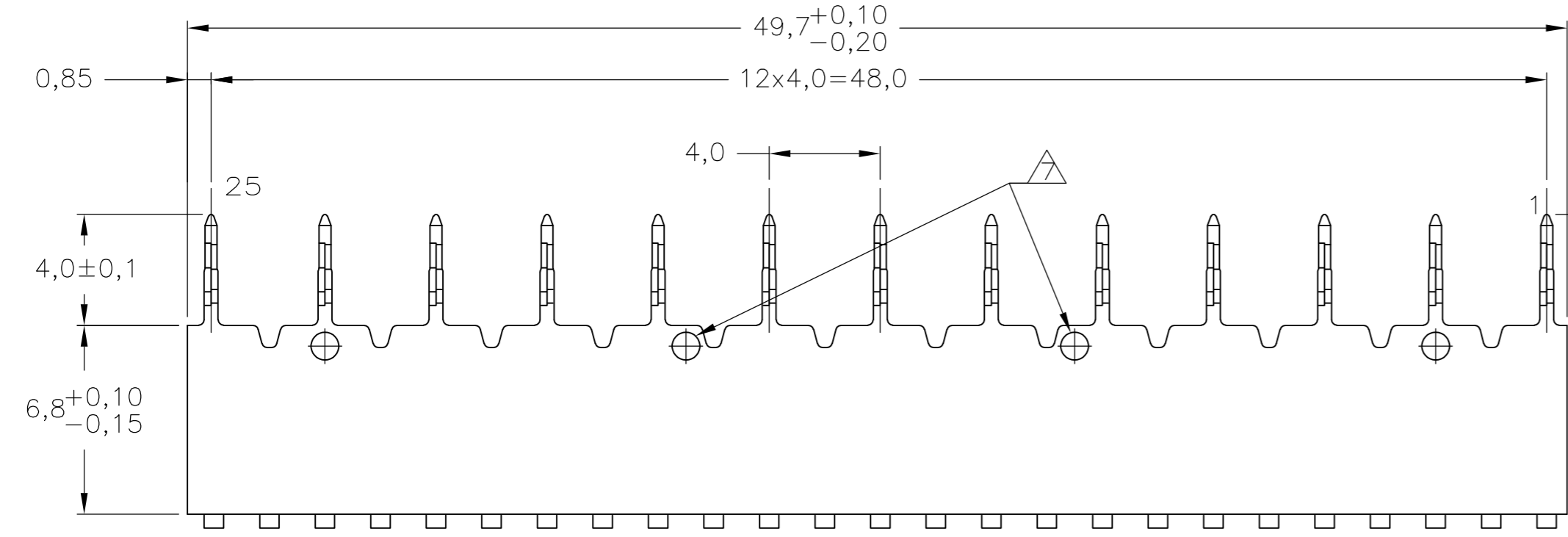


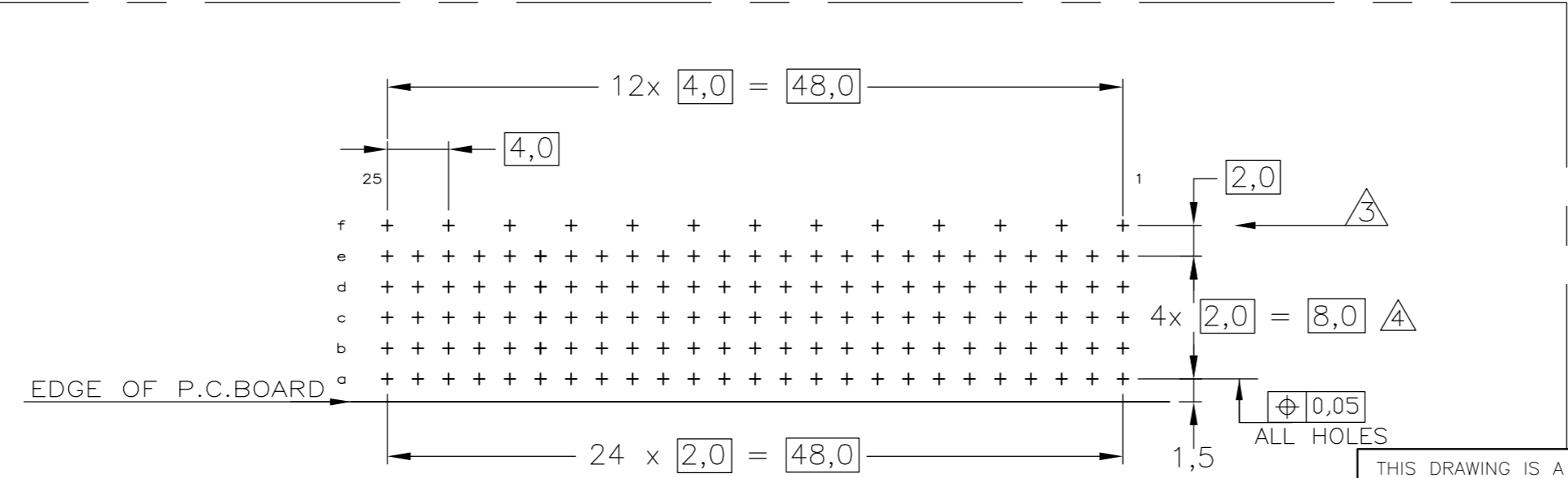
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LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD		
	K	REVISED PER ECO-13-015151	16DEC2013	FL	FY		



NOTES:

- △ GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27µm NICKEL MIN.AND ACTION PIN: 0,5µm TIN-LEAD MIN. FOR PLATING OF MATING SURFACES SEE PERFORMANCE LEVEL SHOWN IN PART NUMBER TABLE.
- △ MATERIAL; PHOSPHORBRONZE.
- △ ROW "f" 13 PLATED THROUGH HOLES FOR UPPERSHIELD
- △ HOLE PATTERN FOR FEMALE CONNECTOR TYPE B-25 COLUMNS 125 PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID SHIELDS LUBRICATED WITH BELLCORE APPROVED LUBRICANT. TECHNICAL REF: TR-NWT-001217 ISSUE 1, SEPT. 1992.
- △ GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27µm NICKEL MIN.AND ACTION PIN: 0,5µm TIN-LEAD MIN. ASTM B579 60/40 FOR PLATING OF MATING SURFACES SEE PERFORMANCE LEVEL SHOWN IN PART NUMBER TABLE.
- △ OPTIONAL DIMPLES AT DISCRETION OF DIE ENGINEER.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI
- △ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 2.
- △ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 1.
- △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL III,CENTRAL OFFICE APPLICATIONS.
- △ 0.76µm MIN GOLD PLATING AT MATING SURFACE.



COMPONENT SIDE AS SHOWN
 RECOMMENDED PCB-HOLE LAY-OUT

P.C.B. HOLE DIM. ACTION PIN
 FOR DETAILS SEE APPLICATION SPECIFICATION

FINISH	MATERIAL	PARTNUMBER
△9△1	△	8-338109-4
△6△5△1	△	1-338109-9
△1△5△1	△	338109-9
△1△9	△	-338109-2-

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN	D. TRUREN	28-11-96
CHK	W. v.d.HEIJDEN	28-11-96
APVD	F. v.KONINGSBRUGGE	
PRODUCT SPEC	108-19082	
APPLICATION SPEC	114-19029	
WEIGHT	-	
CUSTOMER DRAWING		

TE Connectivity

Z-PACK 2mm HM
 GROUND RETURN UPPER SHIELD
 TYPE B-25 COLUMNS

SIZE	A2	CAGE CODE	00779	DRAWING NO	C=338109	RESTRICTED TO	-
SCALE	5:1	SHEET	1 of 1	REV	K		